## 1. General description

Silicon Germanium (SiGe) rectifier encapsulated in a CFP5 (SOD128) small and flat lead Surface-Mounted Device (SMD) plastic package.

### 2. Features and benefits

Features	Benefits					
<ul> <li>Low forward voltage and low Q<sub>rr</sub></li> <li>Extremely low leakage current</li> <li>Thermal stability up to 175 °C junction temperature</li> <li>Fast and smooth switching</li> <li>Low parasitic capacitance</li> <li>AEC-Q101 qualified</li> </ul>	<ul> <li>Excellent efficiency</li> <li>Extraordinary safe operating area</li> <li>Minimal impact on Electro-Magnetic Compatibility (EMC) allowing simplified certification</li> </ul>					

## 3. Applications

- High-efficiency power conversion
  - · Automotive LED lighting
  - Engine control unit
  - Server power supply
  - Base station power supply
- Reverse polarity protection
- OR-ing

## 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; square wave; f = 20 kHz; T <sub>sp</sub> $\leq$ 160 °C		-	-	2	Α
$V_R$	reverse voltage	T <sub>j</sub> = 25 °C		-	-	120	V
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 2 A; T <sub>j</sub> = 25 °C; pulsed	[1]	-	770	840	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 120 V; T <sub>j</sub> = 25 °C; pulsed	[1]	-	0.3	30	nA
		$V_R$ = 120 V; $T_j$ = 150 °C; pulsed	[1]	-	20	200	μA

[1] Very short pulse, in order to maintain a stable junction temperature.



## 5. Pinning information

#### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		K [4] A
2	А	anode	1 2 CFP5 (SOD128)	006aab040

## 6. Ordering information

#### **Table 3. Ordering information**

Type number	Package						
	Name	Description	Version				
PMEG120G20ELP		plastic, surface mounted package; 2 terminals; 4 mm pitch; 3.8 mm x 2.6 mm x 1 mm body	SOD128				

## 7. Marking

#### Table 4. Marking codes

Type number	Marking code
PMEG120G20ELP	E8

## 8. Limiting values

#### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Attention: Stress above one of these maximum values may cause irreversible damage to the device.

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>R</sub>	reverse voltage	T <sub>j</sub> = 25 °C		-	120	V
I <sub>F</sub>	forward current	δ = 1; T <sub>sp</sub> ≤ 155 °C		-	2.8	A
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; square wave; f = 20 kHz; T <sub>sp</sub> ≤ 160 °C		-	2	A
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p$ = 8.3 ms; half sine wave; $T_{j(init)}$ = 25 °C		-	75	A
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1]	-	0.75	W
			[2]	-	1.2	W
Tj	junction temperature			-	175	°C
T <sub>amb</sub>	ambient temperature			-55	175	°C
T <sub>stg</sub>	storage temperature			-65	175	°C

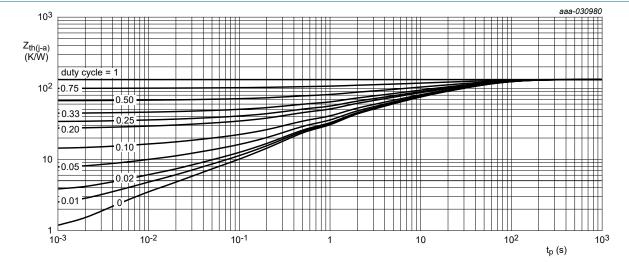
- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

## 9. Thermal characteristics

**Table 6. Thermal characteristics** 

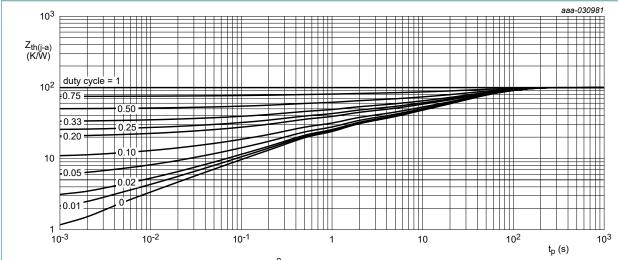
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R <sub>th(j-a)</sub>	thermal resistance from	in free air	[1]	-	-	200	K/W
junction to ambient			[2]	-	-	120	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		[3]	-	-	12	K/W

- Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- Soldering point of cathode tab.



FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

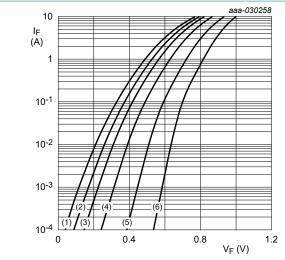
**Table 7. Characteristics** 

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$V_{(BR)R}$	reverse breakdown voltage	I <sub>R</sub> = 1 mA; pulsed; T <sub>j</sub> = 25 °C	[1]	120	-	-	V
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 0.1 A; T <sub>j</sub> = 25 °C; pulsed	[1]	-	590	670	mV
		I <sub>F</sub> = 0.5 A; T <sub>j</sub> = 25 °C; pulsed	[1]	-	680	760	mV
		I <sub>F</sub> = 1 A; T <sub>j</sub> = 25 °C; pulsed	[1]	-	720	800	mV
		I <sub>F</sub> = 2 A; T <sub>j</sub> = 25 °C; pulsed	[1]	-	770	840	mV
		I <sub>F</sub> = 2 A; T <sub>j</sub> = -40 °C; pulsed	[1]	-	860	950	mV
		I <sub>F</sub> = 2 A; T <sub>j</sub> = 125 °C; pulsed	[1]	-	620	720	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 120 V; T <sub>j</sub> = 25 °C; pulsed	[1]	-	0.3	30	nA
		V <sub>R</sub> = 120 V; T <sub>j</sub> = 125 °C; pulsed	[1]	-	3.5	40	μΑ
		V <sub>R</sub> = 120 V; T <sub>j</sub> = 150 °C; pulsed	[1]	-	20	200	μΑ
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C		-	75	-	pF
		V <sub>R</sub> = 10 V; f = 1 MHz; T <sub>j</sub> = 25 °C		-	30	-	pF
t <sub>rr</sub>	reverse recovery time step recovery	$I_F = 0.5 \text{ A}; I_R = 1 \text{ A}; I_{R(meas)} = 0.25 \text{ A};$ $T_j = 25 \text{ °C}$		-	6	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 100 \text{ A/}\mu\text{s}; I_F = 1 \text{ A}; V_R = 30 \text{ V};$ $T_j = 25 ^{\circ}\text{C}$		-	11	-	ns
I <sub>RM</sub>	peak reverse recovery current	_		-	0.7	-	Α
Q <sub>rr</sub>	reverse recovery charge	_		-	5	-	nC
$V_{FRM}$	peak forward recovery voltage	$I_F = 0.5 \text{ A}; dI_F/dt = 20 \text{ A/}\mu\text{s}; T_j = 25 ^{\circ}\text{C}$		-	685	-	mV

<sup>[1]</sup> Very short pulse, in order to maintain a stable junction temperature.

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### 120 V, 2 A Silicon Germanium (SiGe) rectifier



pulsed condition

(1)  $T_i = 175$  °C

(2)  $T_i = 150 °C$ 

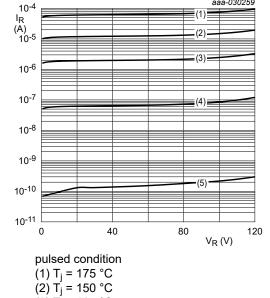
(3)  $T_i = 125 °C$ 

 $(4) T_i = 85 °C$ 

 $(5) T_{i} = 25 ^{\circ}C$ 

(6)  $T_i = -40 \, ^{\circ}\text{C}$ 

Forward current as a function of forward Fig. 3. voltage; typical values



(3)  $T_i = 125 °C$ 

 $(4) T_i = 85 ^{\circ}C$  $(5) T_i = 25 °C$ 

Fig. 4. Reverse current as a function of reverse voltage; typical values

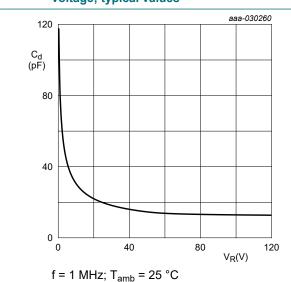
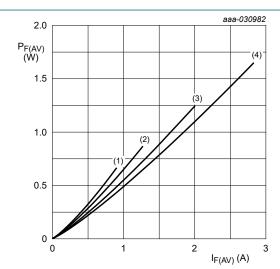


Fig. 5. Diode capacitance as a function of reverse voltage; typical values

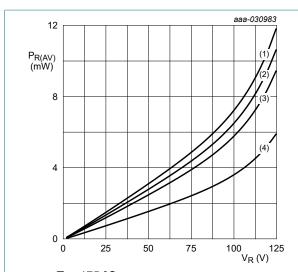


T<sub>i</sub> = 175 °C  $(1) \delta = 0.1$ 

 $(2) \delta = 0.2$ 

 $(3) \delta = 0.5$ (4)  $\delta = 1$ ; DC

Fig. 6. Average forward power dissipation as a function of average forward current; typical values



 $T_j = 175 \,{}^{\circ}\text{C}$ 

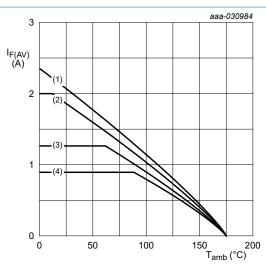
 $(1) \delta = 1; DC$ 

 $(2) \delta = 0.9$ 

 $(3) \delta = 0.8$ 

 $(3) \delta = 0.5$  $(4) \delta = 0.5$ 

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

T<sub>i</sub> = 175 °C

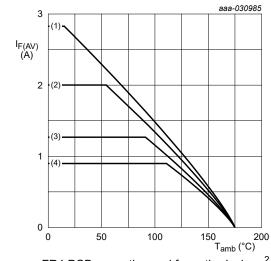
 $(1) \delta = 1; DC$ 

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

T<sub>i</sub> = 175 °C

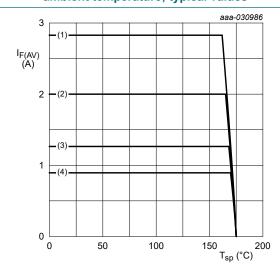
 $(1) \delta = 1$ ; DC

 $(2) \delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



 $T_i = 175 \,{}^{\circ}\text{C}$ 

 $(1) \delta = 1; DC$ 

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

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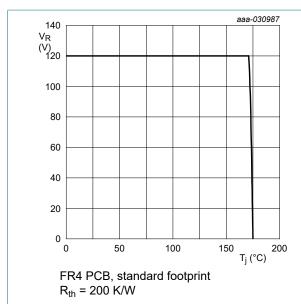
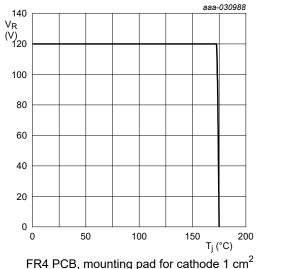
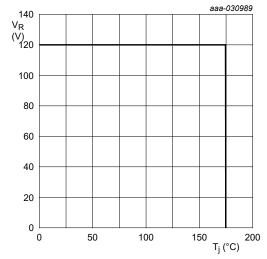


Fig. 11. Derated maximum reverse voltage as a function | Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  $R_{th} = 120 \text{ K/W}$ 

of junction temperature; typical values



Soldering point of cathode tab  $R_{th} = 12 \text{ K/W}$ 

Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values

## 11. Test information

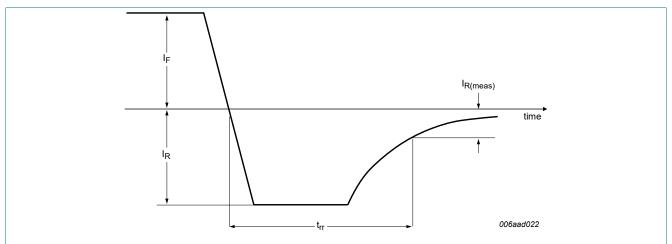


Fig. 14. Reverse recovery definition; step recovery

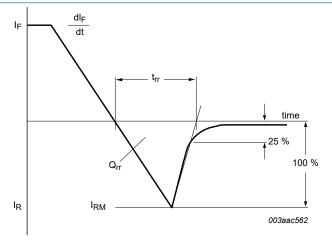


Fig. 15. Reverse recovery definition; ramp recovery

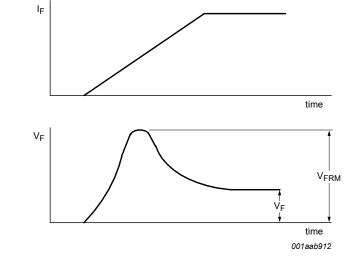
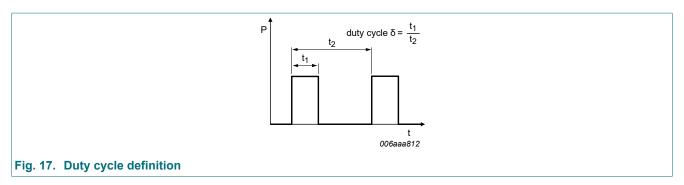


Fig. 16. Forward recovery definition



The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current

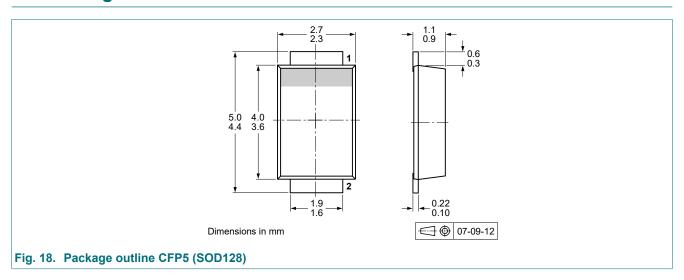
 $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$ 

with  $I_{\text{RMS}}$  defined as RMS current.

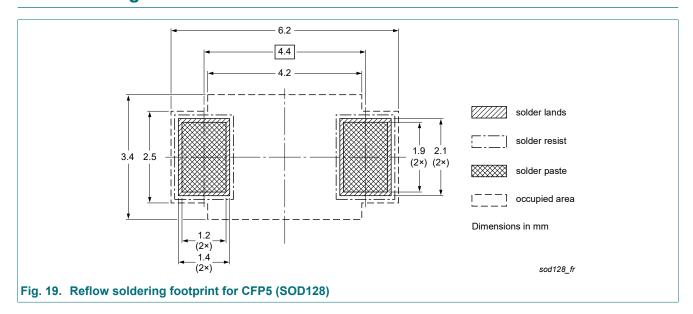
## **Quality information**

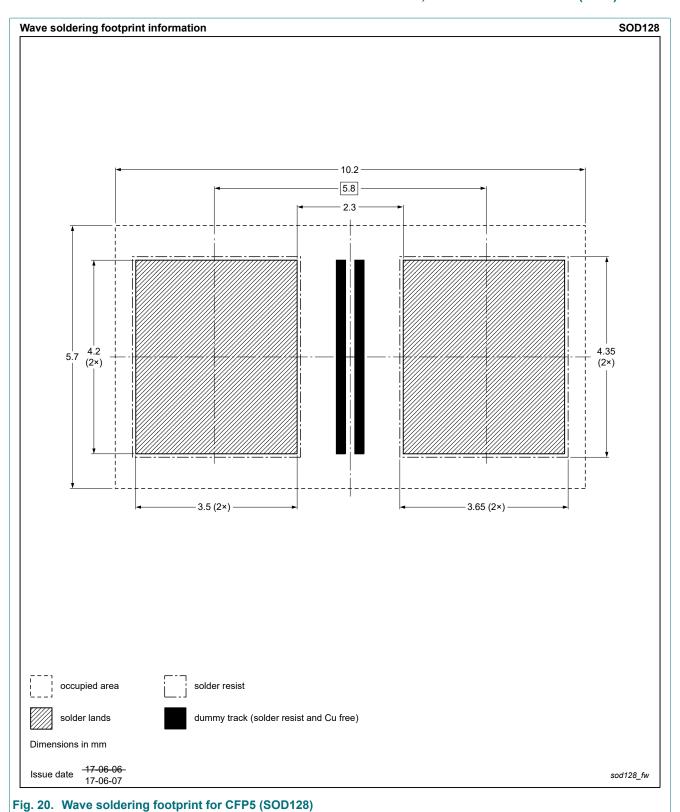
This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

## 12. Package outline



# 13. Soldering





## 14. Mounting

This device is sensitive to Electro Static Discharge (ESD). Observe precautions for handling electrostatic sensitive devices. Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

# 15. Revision history

## Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG120G20ELP v.1	20200526	Product data sheet	-	-

## 16. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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### 120 V, 2 A Silicon Germanium (SiGe) rectifier

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